

SOT601-1

plastic thin fine-pitch ball grid array package; 280 balls; body
16 x 16 x 0.8 mm

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|---|
| Terminal position code | B (bottom) |
| Package type descriptive code | TFBGA280 |
| Package type industry code | TFBGA280 |
| Package style descriptive code | TFBGA (thin fine-pitch ball grid array) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MO-216 |
| Mounting method type | S (surface mount) |
| Issue date | 9-7-2003 |

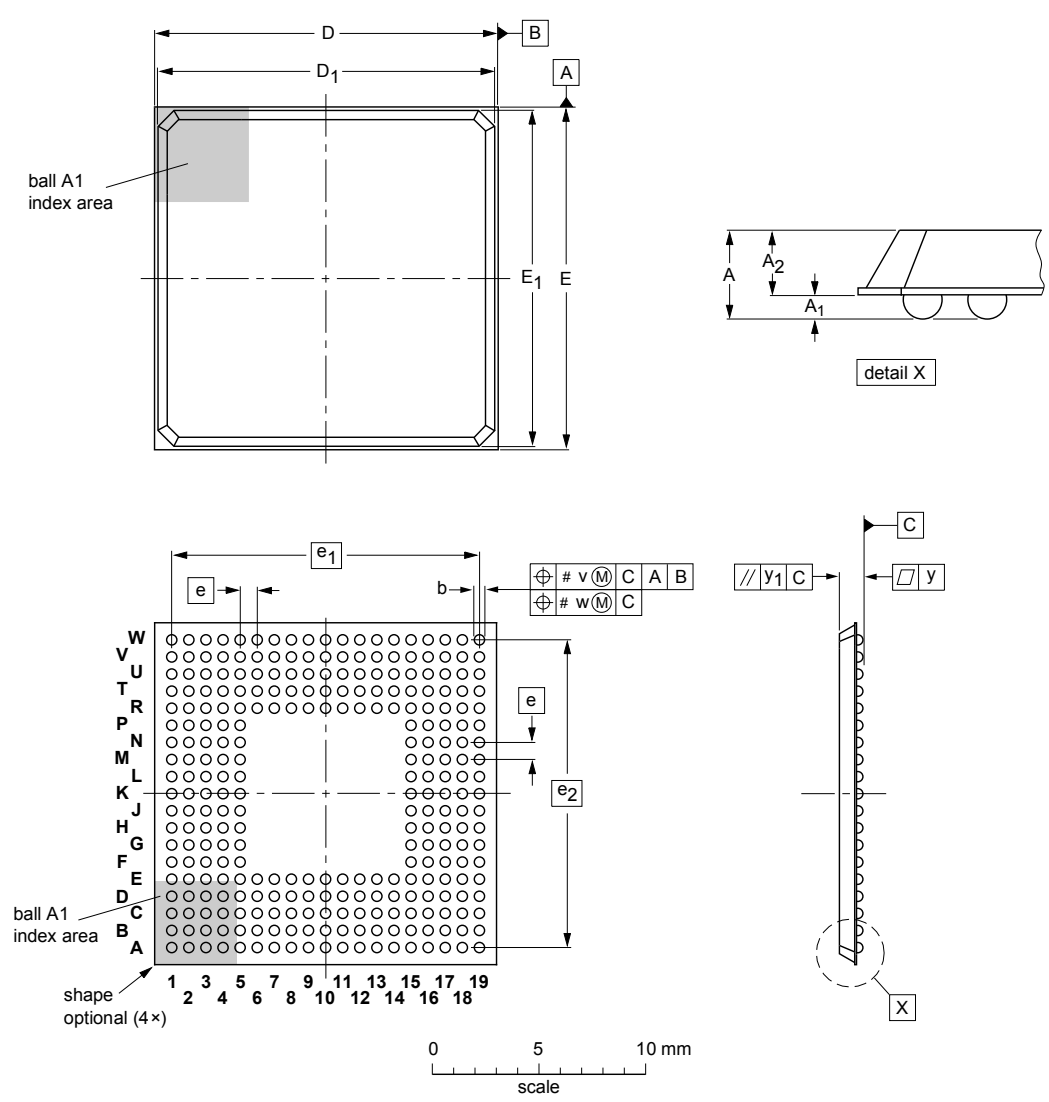
Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-------|-----|-----|------|------|
| D | package length | 15.8 | - | 16 | 16.2 | mm |
| E | package width | 15.8 | - | 16 | 16.2 | mm |
| A | seated height | [tbd] | - | 1.2 | 1.2 | mm |
| A ₂ | package height | 0.76 | - | 0.8 | 0.84 | mm |
| n ₂ | actual quantity of termination | - | - | 280 | - | |



2. Package outline

TFBGA280: plastic thin fine-pitch ball grid array package; 280 balls; body 16 x 16 x 0.8 mm SOT601-1



DIMENSIONS (mm are the original dimensions)

| UNIT | A max. | A ₁ | A ₂ | b | D | D ₁ | E | E ₁ | e | e ₁ | e ₂ | v | w | y | y ₁ |
|------|-----------|----------------|----------------|--------------|--------------|----------------|--------------|----------------|-----|----------------|----------------|------|------|------|----------------|
| mm | 1.2 | 0.36 0.24 | 0.84 0.76 | 0.53 0.43 | 16.2 15.8 | 15.9 15.7 | 16.2 15.8 | 15.9 15.7 | 0.8 | 14.4 | 14.4 | 0.15 | 0.08 | 0.15 | 0.1 |

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|--------------------|------------|--------|-------|--|------------------------|----------------------|
| | IEC | JEDEC | JEITA | | | |
| SOT601-1 | | MO-216 | | | | 03-03-03 03-07-09 |

Fig. 1. Package outline TFBGA280 (SOT601-1)

3. Soldering

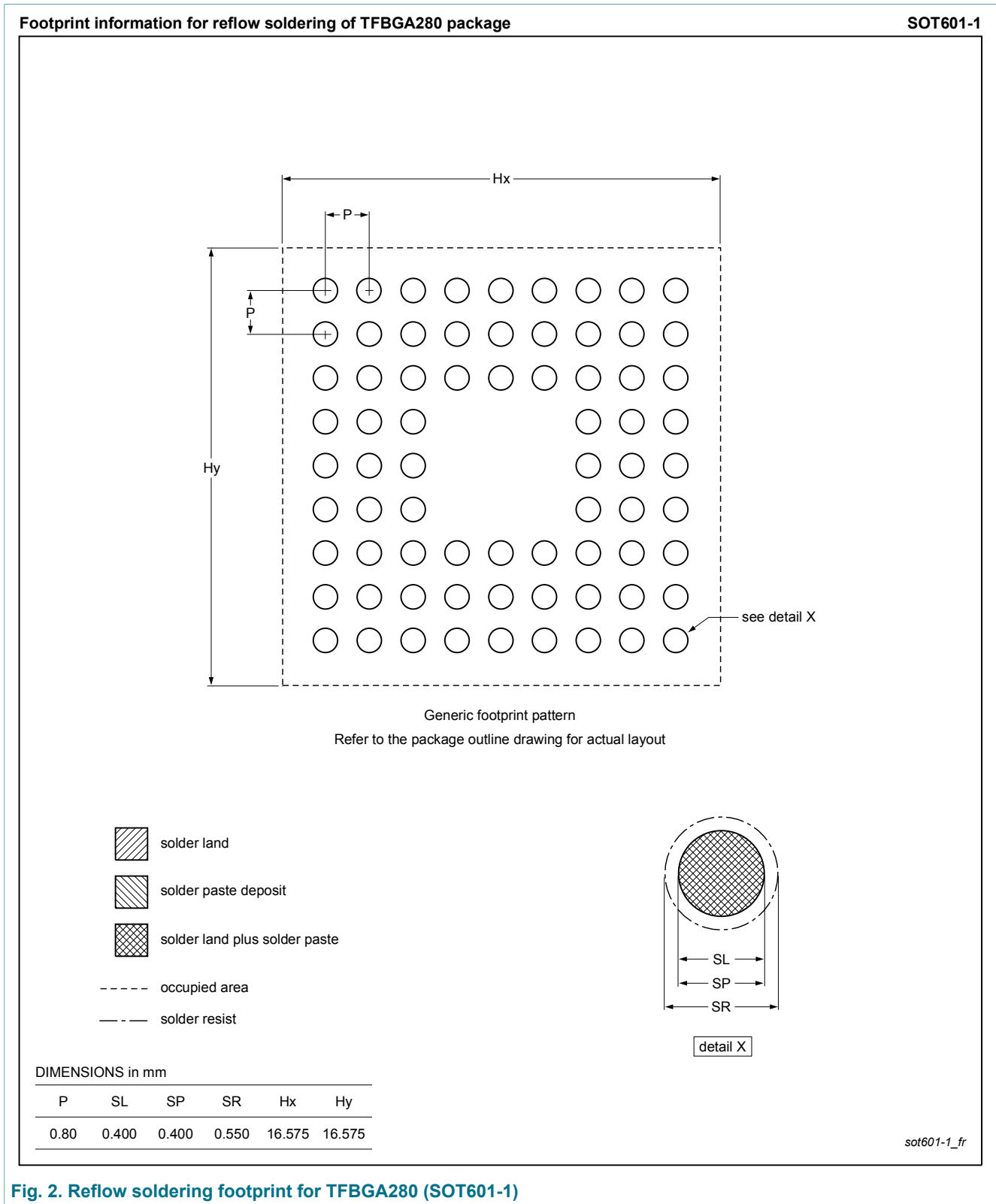


Fig. 2. Reflow soldering footprint for TFBGA280 (SOT601-1)

4. Legal information

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